

WAFER PROCESSING METHOD

ABSTRACT

A wafer processing method including a first correction step of measuring a distance a between a first cut groove previously formed by a first cutting unit in a cutting step and a division line where the first cut groove is to be next formed, and correcting an actual index amount of the first cutting unit by using a deviation b of the first cutting unit equivalent to the difference between the distance a and a proper index amount of the first cutting unit during the cutting step; and a second correction step of forming a measurement groove by using a second cutting unit along the division line where the first cut groove is to be next formed, measuring a distance c between the first cut groove previously formed and the measurement groove, and correcting an actual index amount of the second cutting unit by using a deviation d of the second cutting unit equivalent to the difference between the distance c and a proper index amount of the second cutting unit during the cutting step is provided.

(Figure 4)